

L Number	Hits	Search Text	DB	Time stamp
1	8993	((Chemical adj mechanical adj polish\$3) or CMP or planariz\$5) and (slurry or composition)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/02/08 14:56
8	29	((Chemical adj mechanical adj polish\$3) or CMP or planariz\$5) and (slurry or composition)) and (periodic adj acid)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/02/08 14:57
15	1	((Chemical adj mechanical adj polish\$3) or CMP or planariz\$5) and (slurry or composition)) and (periodic adj acid)) and (ammonium adj nitrate\$1)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/02/08 15:10
22	18	((Chemical adj mechanical adj polish\$3) or CMP or planariz\$5) and (slurry or composition)) and (periodic adj acid)) and ((ammonium adj nitrate\$1)or (ammonium near3 salt\$1))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/02/08 15:12